

TK15A60U

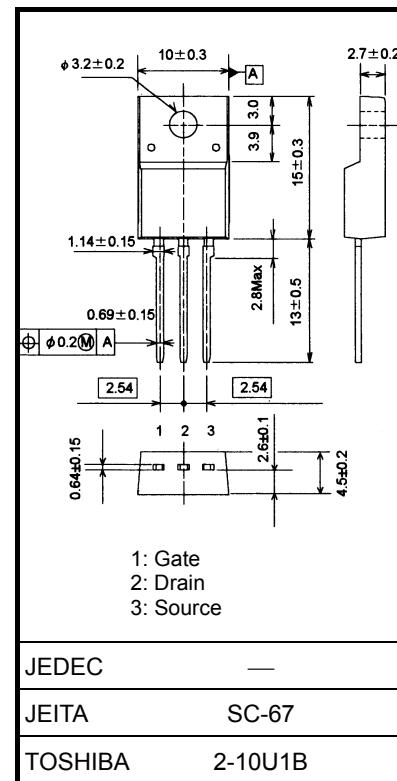


Switching Regulator Applications

- Low drain-source ON-resistance: $R_{DS\ (ON)} = 0.24\ \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 8.5\ S$ (typ.)
- Low leakage current: $I_{DSS} = 100\ \mu A$ ($V_{DS} = 600\ V$)
- Enhancement mode: $V_{th} = 3.0$ to $5.0\ V$ ($V_{DS} = 10\ V$, $I_D = 1\ mA$)

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Characteristics	Symbol	Rating	Unit
Drain-source voltage	V_{DSS}	600	V
Gate-source voltage	V_{GSS}	± 30	V
Drain current	DC (Note 1) I_D	15	A
	Pulse ($t = 1\ ms$) (Note 1) I_{DP}	30	
Drain power dissipation ($T_c = 25^\circ C$)	P_D	40	W
Single pulse avalanche energy (Note 2)	E_{AS}	81	mJ
Avalanche current (Note 3)	I_{AR}	15	A
Repetitive avalanche energy	E_{AR}	4	mJ
Channel temperature	T_{ch}	150	$^\circ C$
Storage temperature range	T_{stg}	-55 to 150	$^\circ C$



Weight: 1.7 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

Thermal Characteristics

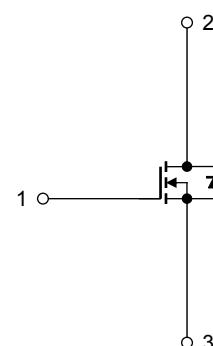
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	$R_{th\ (ch-c)}$	3.125	$^\circ C/W$
Thermal resistance, channel to ambient	$R_{th\ (ch-a)}$	62.5	$^\circ C/W$

Note 1: Ensure that the channel temperature does not exceed $150^\circ C$.

Note 2: $V_{DD} = 90\ V$, $T_{ch} = 25^\circ C$ (initial), $L = 0.63\ mH$, $R_G = 25\ \Omega$, $I_{AR} = 15\ A$

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit	
Gate leakage current	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V	—	—	±1	µA	
Drain cut-off current	I _{DSS}	V _{DS} = 600 V, V _{GS} = 0 V	—	—	100	µA	
Drain-source breakdown voltage	V _{(BR) DSS}	I _D = 10 mA, V _{GS} = 0 V	600	—	—	V	
Gate threshold voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	3.0	—	5.0	V	
Drain-source ON-resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 7.5 A	—	0.24	0.3	Ω	
Forward transfer admittance	Y _{fs}	V _{DS} = 10 V, I _D = 7.5 A	3.0	8.5	—	S	
Input capacitance	C _{iss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	—	950	—	pF	
Reverse transfer capacitance	C _{rss}		—	47	—		
Output capacitance	C _{oss}		—	2300	—		
Switching time	Rise time	t _r	 10 V V _{GS} 0 V 50 Ω I _D = 7.5A R _L = 40Ω V _{DD} ≈ 300 V Duty ≤ 1%, t _W = 10 µs	—	37	—	ns
	Turn-ON time	t _{on}		—	80	—	
	Fall time	t _f		—	8	—	
	Turn-OFF time	t _{off}		—	105	—	
Total gate charge	Q _g	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 15 A	—	17	—	nC	
Gate-source charge	Q _{gs}		—	10	—		
Gate-drain charge	Q _{gd}		—	7	—		

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Typ.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	—	—	15	A
Pulse drain reverse current (Note 1)	I _{DRP}	—	—	—	30	A
Forward voltage (diode)	V _{DSF}	I _{DR} = 15 A, V _{GS} = 0 V	—	—	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 15 A, V _{GS} = 0 V, dI _{DR} /dt = 100 A/µs	—	530	—	ns
Reverse recovery charge	Q _{rr}		—	9.0	—	µC

Marking